

Abstract

Substrate Independent SuperPolishing Process
and Slurry

The present invention utilizes a combination of chemical and mechanical finishing processes to polish a disk substrate surface to near atomic smoothness. Broadly speaking, the surface of a disk substrate that has been machined (i.e., rough ground) to a predetermined surface roughness is subjected to attack by a chemical formulation (called an attacking agent). The chemical formulation is used to soften the substrate material. Then, the softened material is "wiped away" via mechanical action.

FIG. 1